SOT146-1

plastic dual in-line package; 20 leads (300 mil)

21 April 2016 Package information

1. Package summary

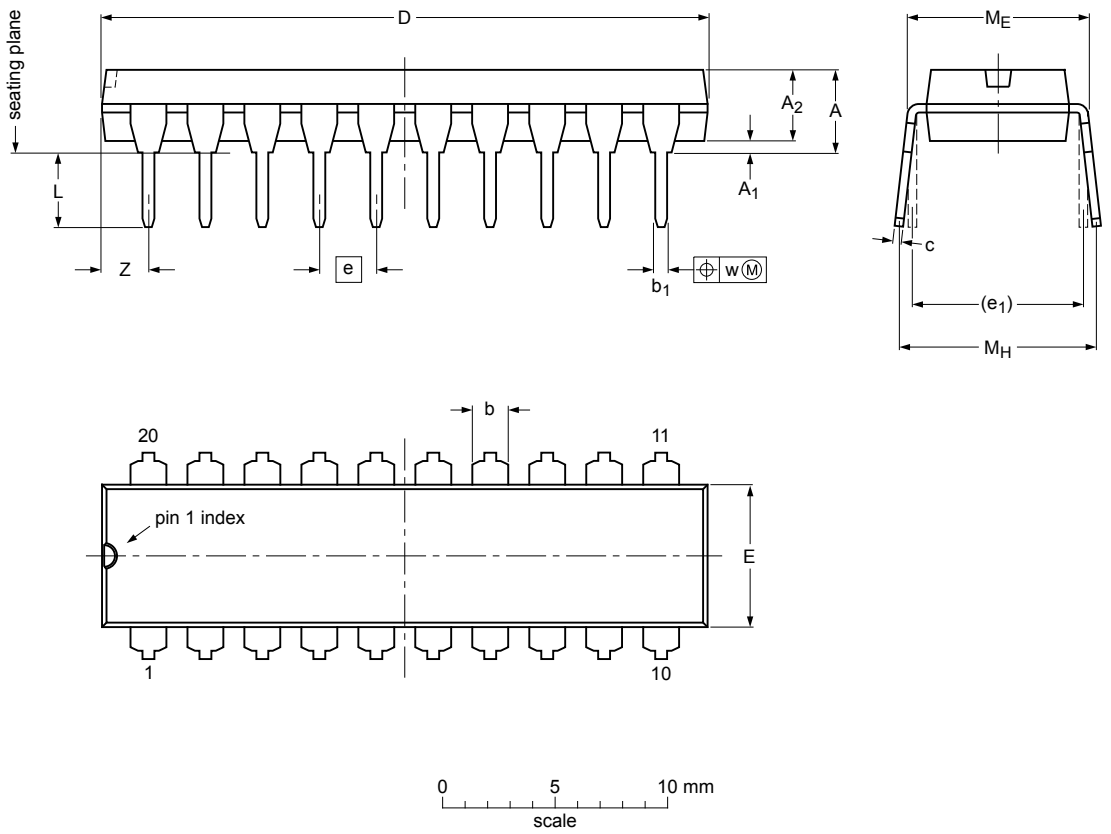
Terminal position code	D (double)
Package type descriptive code	DIP20
Package type industry code	DIP20
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-001
JEITA package outline code	SC-603
Mounting method type	T (through-hole mount)
Issue date	13-2-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		26.03	-	-	26.29	mm
E	package width		6.22	-	6.35	6.4	mm
A	seated height		-	-	4.2	4.2	mm
A_2	package height		-	-	3.04	3.2	mm
e	nominal pitch		-	-	-	-	
n_2	actual quantity of termination		-	-	20	-	

2. Package outline

DIP20: plastic dual in-line package; 20 leads (300 mil) **SOT146-1**



Dimensions (mm are the original dimensions)

Unit(1)		A	A_1	A_2	b	b_1	c	D(1)	E(1)	e	e_1	L	M_E	M_H	w	Z(1)
mm	max	4.2		3.2	1.73	0.53	0.36	26.29	6.40			3.60	8.25	10.0		2
	nom									2.54	7.62				0.254	
	min		0.51		1.30	0.38	0.23	26.03	6.22			3.05	7.80	8.3		

Note
1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

sot146-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT146-1		MS-001	SC-603			~~03-02-13~~ 15-12-10

Fig. 1. Package outline DIP20 (SOT146-1)

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